



## Material Content Data Sheet



<b>Sales Product Name</b>				IAUA250N04S6N007		<b>Issued</b>		1. September 2019	
<b>MA#</b>				MA003227216					
<b>Package</b>				PG-HSOF-5-4		<b>Weight*</b>		370.30 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.845	1.04	1.04	10383	10383	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.00		39		
	non noble metal	iron	7439-89-6	0.048	0.01		131		
	non noble metal	copper	7440-50-8	48.418	13.08	13.09	130754	130924	
	noble metal	gold	7440-57-5	0.034	0.01	0.01	93	93	
wire	organic material	carbon black	1333-86-4	2.096	0.57		5661		
encapsulation	plastics	epoxy resin	-	23.058	6.23		62268		
	inorganic material	silicondioxide	60676-86-0	114.590	30.95	37.75	309455	377384	
leadfinish	non noble metal	tin	7440-31-5	3.673	0.99	0.99	9919	9919	
plating	noble metal	silver	7440-22-4	0.015	0.00	0.00	41	41	
solder	non noble metal	tin	7440-31-5	0.068	0.02		185		
	noble metal	silver	7440-22-4	0.085	0.02		231		
	non noble metal	lead	7439-92-1	3.266	0.88	0.92	8820	9236	
	inorganic material	phosphorus	7723-14-0	0.008	0.00		23		
heat sink clip	non noble metal	iron	7439-89-6	0.028	0.01		76		
	non noble metal	copper	7440-50-8	28.224	7.62	7.63	76220	76319	
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116		
	non noble metal	iron	7439-89-6	0.143	0.04		386		
	non noble metal	copper	7440-50-8	142.638	38.52	38.57	385199	385701	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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